MA3D749 (MA7D49), MA3D749A (MA7D49A)

Silicon epitaxial planar type (cathode common)

For switching mode power supply

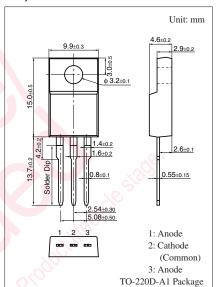
■ Features

- Low forward voltage V_F
- High dielectric breakdown voltage: > 5 kV
- Easy-to-mount, due to its V cut lead end

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Repetitive peak	MA3D749	V _{RRM}	40	V	
reverse voltage	MA3D749A		45		
Forward current (Average)		I _{F(AV)}	5	A	
Non-repetitive peak forward surge current *		I_{FSM}	90	A	
Junction temperature		T_{j}	-40 to +125	°C	
Storage temperature		T_{stg}	-40 to +125	°C	

Note) *: Half sine wave; 10 ms/cycle

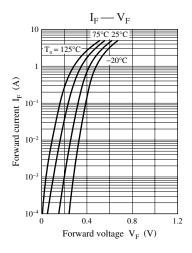


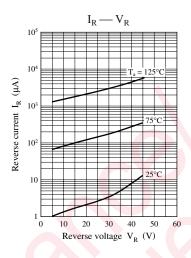
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 2^{\circ}C$

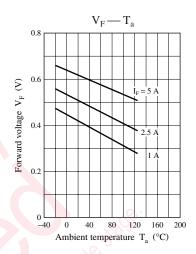
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		$V_{\rm F}$	$I_F = 2.5 \text{ A}, T_C = 25^{\circ}\text{C}$	000	0,,	0.55	V
Reverse current	MA3D749	I_R	$V_R = 40 \text{ V}, T_C = 25^{\circ}\text{C}$	y. "(0.	1.0	mA
	MA3D749A	SO	$V_R = 45 \text{ V}, T_C = 25^{\circ}\text{C}$	160		1.0	
Thermal resistance (j-c) R _{th(j-c)}		3.0	°C/W				

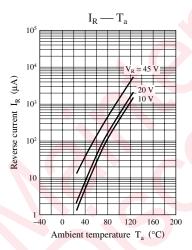
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 200 MHz.

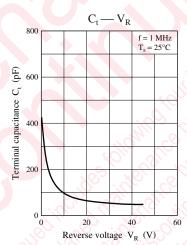
Note) The part numbers in the parenthesis show conventional part number.

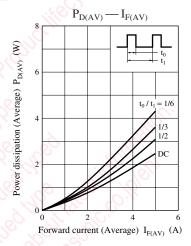


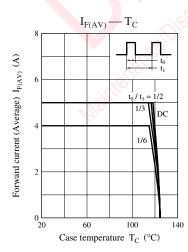












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